

removing the silicon wafer from the nozzle part; and
adhering the membrane to a heat driving part to form the fluid jetting apparatuses as a continuous piece to be split into separate fluid jetting apparatuses.

27. (TWICE AMENDED) A process of manufacturing a plurality of fluid jetting apparatuses, comprising:

forming a nozzle part on a first substrate of silicon wafer by a spinning process;
forming a membrane on a second substrate of silicon wafer by the spinning process;
forming a heat driving part by forming electrodes and heat elements on a third substrate of silicon wafer; and

adhering the nozzle part to the membrane, and the membrane to the heat driving part to form the fluid jetting apparatuses as a continuous piece to be separated into individual fluid jetting apparatuses.

31. (ONCE AMENDED) A process of manufacturing a plurality of fluid jetting apparatuses, comprising:

adhering a nozzle part to a membrane as a wafer type; and
adhering the membrane to a heat driving part, to form the fluid jetting apparatuses as a continuous wafer to be separated into individual fluid jetting apparatuses.

45. (ONCE AMENDED) A process of forming fluid jetting apparatuses, comprising:

adhering a nozzle part having nozzles to a membrane; and
adhering the membrane to a heat driving part to form fluid jetting apparatuses to form a continuous piece with each fluid jetting apparatus having one of the nozzles.

REMARKS

INTRODUCTION:

In accordance with the foregoing, claims 1, 17, 27, 31, and 45 have been amended to clarify an existing limitation and not to narrow the scope of the claim. No new matter is being presented, and approval and entry are respectfully requested.

Claims 1, 2, 13-17, 19, 21, 23, 24, 27, 30, 31, and 38, 40, 42, 44, 45, and 47 are pending and under consideration. Reconsideration is requested.